

Circuit housing

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CLAIMS

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1. Miniaturized circuit housing to encapsulate and provide external contacts for at least one integrated circuit, in particular of the flip-chip or wafer-level-package type, with a housing floor, the lower surface of which bears housing contact elements for making external contact and the upper surface of which is electrically connected to circuit contact elements on the lower surface of the circuit, characterized in that a housing lid is provided, in particular opposite the housing floor, which presses the circuit with the circuit contact element resiliently against the upper surface of the housing floor, and between the circuit contact elements and the housing floor there is no connection that fixes their materials permanently together.
 2. Circuit housing according to Claim 1, characterized in that the housing lid on its lower surface, which faces the circuit, comprises at least one spring element that presses the circuit against the housing floor.
 3. Circuit housing according to Claim 2, characterized in that the spring element or elements is/are fixedly attached to the lower surface of the housing lid.
 4. Circuit housing according to Claim 2, characterized in that the spring element or elements is/are loosely inserted between housing lid and circuit.

5. Circuit housing according to claim 1, characterized in that the housing lid can itself act as a spring because of its flexible construction.

6. Circuit housing according to claim 1, characterized by a wall that substantially rigidly connects floor and lid of the housing to one another at their circumference and tightly seals off the interior of the housing.

7. Circuit housing according to Claim 6, characterized in that the wall is formed as part, particularly an integral part, of the housing floor or lid and is sealed to the respective other housing component in a gas-tight manner.

8. Circuit housing according to Claim 7, characterized in that the seal is formed by an external plastic encapsulation of at least the butt joint between the housing lid or housing floor and the wall.

9. Circuit housing according to claim 1, characterized by being filled with a medium that is slow to react, in particular an inert gas.

10. Circuit housing according to claim 1, characterized by a flat four-cornered shape, with substantially level and rectangular housing floor and housing lid.

11. Circuit housing according to claim 1,
characterized in that the lid of the housing is rigidly
constructed and joined to the wall, or is shielded by a

rigid covering, in such a way that externally applied force is not transmitted to the circuit.

12. Circuit housing according to claim 1,
characterized in that the lid of the housing is constructed
as a heat sink in order to cool the circuit, in particular
bears cooling ribs or similar area-increasing structures.

13. Circuit housing according to claim 1,
characterized by a construction of the housing lid and/or
the spring element or elements such that the pressing force
exerted by these components between the circuit and the
housing floor is adjusted to suit the material of which the
circuit contact elements are made, in particular regarding
their flow behaviour and shape, in order to maintain a
permanently good electrical contact between the circuit
contact elements and the housing floor.

14. Circuit housing according to claim 1,
characterized in that the housing contact elements have
substantially the shape of a sphere or section of a sphere,
like solder balls.

15. Circuit housing according to claim 1,
characterized in that the housing contact elements are
constructed substantially as contact pins or flat contact
surfaces.

16. Circuit housing according to claim 1,
characterized in that the housing floor is constructed as a
circuit board or a section thereof.

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~~particular of the flip-chip type, and a circuit housing~~
~~according to one of the preceding claims,~~
~~characterized in that the circuit contact elements are~~
~~constructed in the nature of bumps and consist~~
~~substantially of gold or a gold alloy.~~

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